



HSD226

Silicon Schottky Barrier Diode for High Speed Switching

REJ03G0603-0400

Rev.4.00

Feb 06, 2007

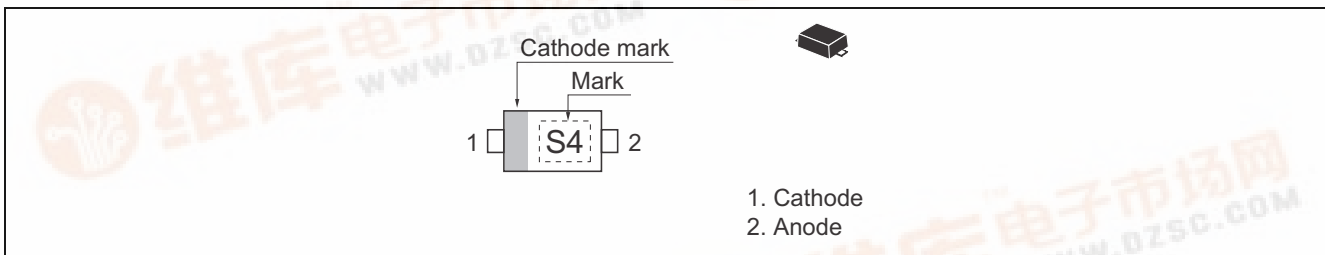
Features

- Low Power consumption (Low reverse leak current) and high speed (Low capacitance).
- Lineup of Environmental friendly Halogen free type (HSD226-N)
- Super small Flat Lead Package (SFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code
HSD226	S4	SFP	PUSF0002ZB-A
HSD226-N (Halogen-free type)			

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Repetitive peak reverse voltage	V_{RRM}	25	V
Non-Repetitive peak forward surge current	I_{FSM}^*	200	mA
Forward current	I_F	50	mA
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	-55 to +125	°C

Note: 10 ms sine wave 1 pulse

Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_{F1}	—	—	0.33	V	$I_F = 1 \text{ mA}$
	V_{F2}	—	—	0.38	V	$I_F = 5 \text{ mA}$
Reverse current	I_R	—	—	450	nA	$V_R = 20 \text{ V}$
Capacitance	C	—	—	2.80	pF	$V_R = 1 \text{ V}, f = 1 \text{ MHz}$

Note: For SFP package, the material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

Main Characteristic

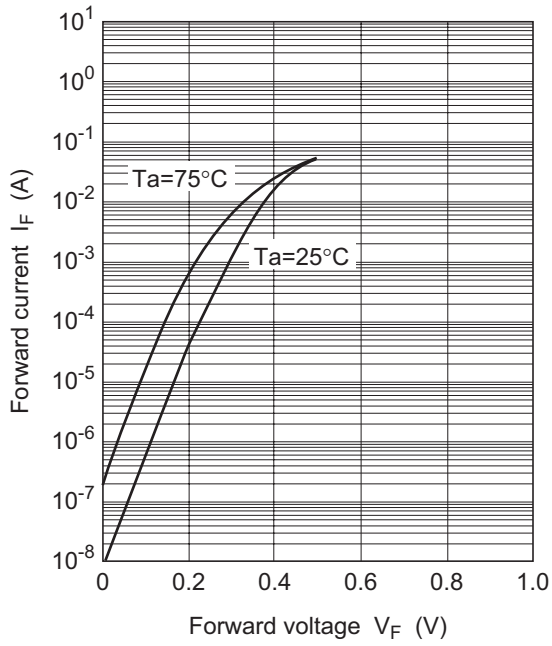


Fig.1 Forward current vs. Forward voltage

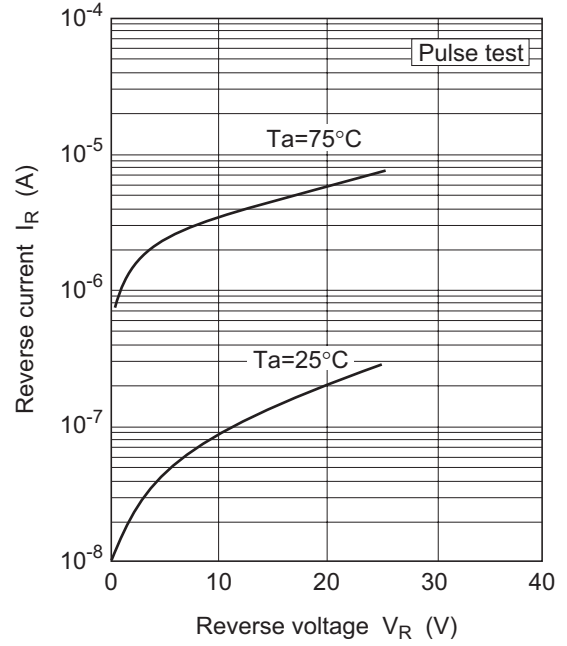


Fig.2 Reverse current vs. Reverse voltage

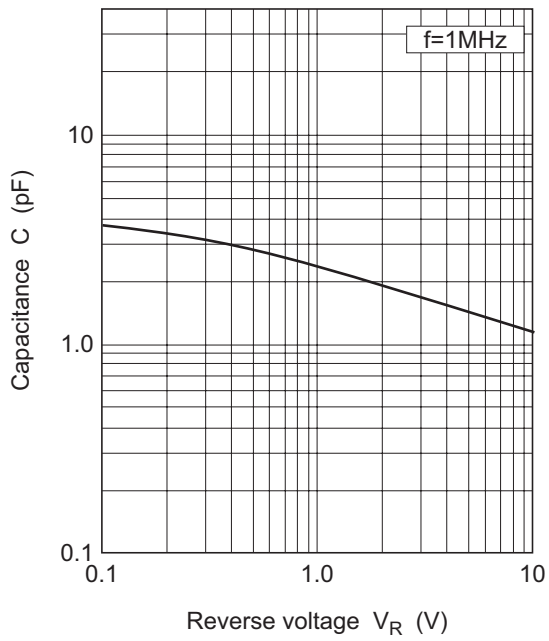
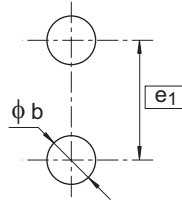
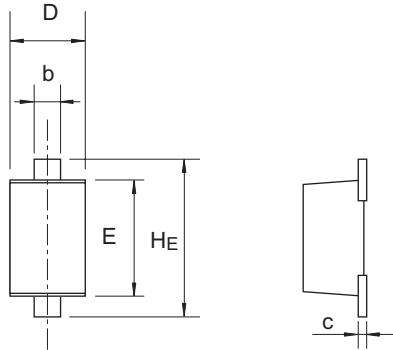


Fig.3 Capacitance vs. Reverse voltage

Package Dimensions

Package Name	JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
SFP	—	PUSF0002ZB-A	SFP / SFPV	0.0010g



Pattern of terminal position areas

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
A	0.50	—	0.55
b	0.25	0.30	0.35
c	0.08	0.13	0.18
D	0.55	0.60	0.65
E	0.90	1.00	1.10
HE	1.30	1.40	1.50
ϕb	—	0.50	—
e1	—	1.40	—

Notes:

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